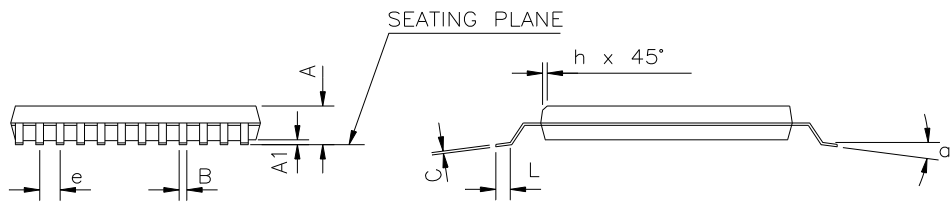
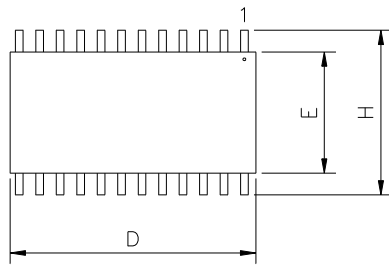


300 MIL SOIC
PLASTIC SMALL OUTLINE GULLWING

PACKAGE INFORMATION

NOTES

1. LEAD WIDTH AND LEAD THICKNESS EXCLUSIVE OF SOLDER PLATE
2. PACKAGE OUTLINE EXCLUSIVE OF MOLD FLASHES AND BURR DIMENSIONS
3. ALLOWABLE MOLD FLASH IS 5 MILS PER SIDE.
4. DIMENSIONS ARE GIVEN IN INCHES.
5. LEAD COPLANARITY IS 0.003 INCH MAX.



JEDEC #	MS-013AC	
TYPE	20 LEAD	
SYMBOL	Min	Max
A	0.096	0.104
A1	0.005	0.011
B	0.014	0.019
C	0.009	0.012
D	0.500	0.510
E	0.292	0.299
e	0.050 BSC	
H	0.396	0.416
h	0.010	0.016
L	0.020	0.040
α°	0	8°

PREPARED BY	NK	REF. NO.	REV. NO.	SPEL SEMICONDUCTOR LIMITED INDIA
CHECKED BY	SP	DIM-SOIC-01	1	
APPROVED BY	NJC		DATE	

